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(54) **ORGANIC ELECTRONIC PACKAGES HAVING HERMETICALLY SEALED EDGES AND METHODS OF MANUFACTURING SUCH PACKAGES**

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H01L 23/58 (2006.01)

(52) **U.S. Cl.**
USPC **257/642**; 257/E51.022; 257/40; 438/82; 428/411.1

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USPC 257/E51.001, E51.012, E51.018, 257/E51.022, E25.008, 40, 94, 99, 100, 257/642; 438/82, 99, 725, 780; 428/411.1, 428/412, 421, 422, 422.8, 451, 473.5, 520
See application file for complete search history.

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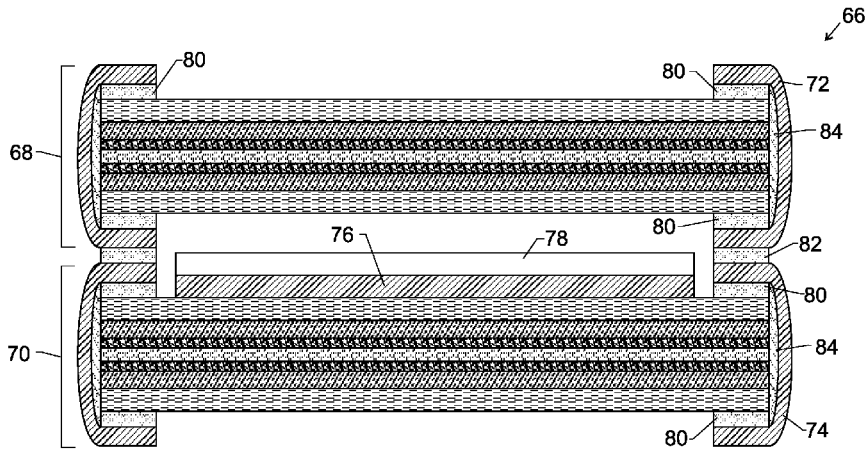
(57) **ABSTRACT**

Organic electronic packages having sealed edges. More specifically, packages having organic electronic devices are provided. A number of sealing mechanisms are provided to hermetically seal the edges of the package to completely protect the organic electronic device from external elements. A sealant may be implemented to completely surround the organic electronic device. Alternatively, edge wraps may be provided to completely surround the organic electronic device.

27 Claims, 6 Drawing Sheets